

Particle Interconnect

- Easy to clean Pb free sockets
- CSP, Chip Scale Package sockets to 0.2mm pitch
- 40 GHz RF test sockets
- MEMS applications
- Same socket from hand test to production
- High density mass interconnect
- Replacement contacts for all handler models



exatron

Please visit
www.pisockets.com
for more information

1-800-EXA-TRON 1-408-629-7600



Particle Interconnect

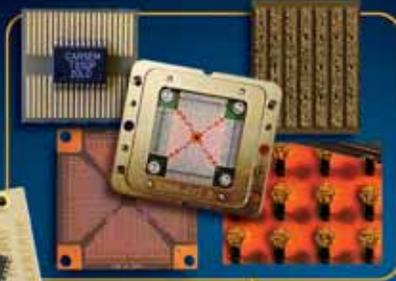
Standard Test Sockets



CSP Sockets



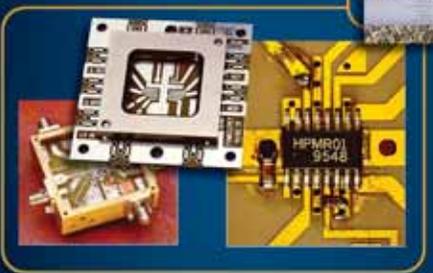
Universal Test Sockets



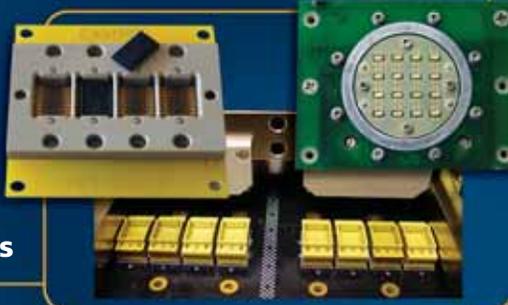
MEMS Sockets



RF "Zero" Sockets



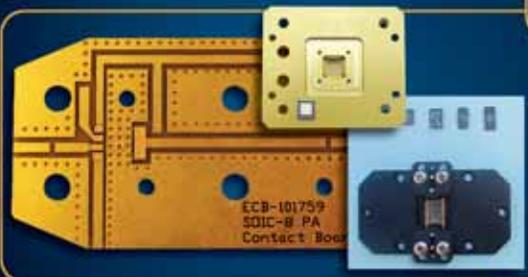
Multi-Site Sockets



High Density Interconnect



Replacement Handler Contacts



EMI Shielding



BeCu Spring Contacts



PI technology begins with 15 micron metal coated diamond particles. These diamond particles are selectively electroplated onto the substrate area using a modified PCB process. PI creates a "micro bed-of-nails" with 50,000 contact points per square inch. It makes a gas-tight electrical contact by penetrating the oxide layer, rather than the traditional wiping action of standard contactors. PI produces contact resistance below 3 milliohms.



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Exatron is the exclusive worldwide licensee under several U.S. Patents for the manufacture and sale of Particle Interconnect™ in sockets used in automated handling and testing of integrated circuits. In addition, Exatron is licensed to produce any device incorporating Particle Interconnect in an electronically-conductive application. Exatron operates it's own manufacturing facility for PI technology.



All Exatron products are RoHS Compliant